

Listing of Claims

This listing of claims will replace all prior versions, and listing, of claims in the application.

1. (Currently Amended) A method for manufacturing a printed wiring board, comprising the steps of: using a carbon dioxide laser to form recess via holes in external copper foils of a copper clad laminate; plating said copper clad laminate to form interlayer electrical connections; forming etching resist layers; exposing and developing the etching resist layers; and thereafter effecting a circuit etching treatment, wherein the copper clad laminate is a laminate formed by using waved copper foils having a surface roughness (R_z) of 2.0 to 20 μm exposed to said carbon dioxide laser as external copper foils.

2. (Original) A method for manufacturing a printed wiring board according to claim 1, wherein each waved copper foil for use in forming the external copper foils of the copper clad laminate includes a bulk copper layer forming a conductor circuit of the printed wiring board, an amount of fine copper particles for ensuring an adhesion strength between the bulk copper layer and a resin substrate, and a rust preventive layer, said bulk copper layer having a thickness of 18 μm or less.

3. (Cancelled).

4. (Currently Amended) A method for manufacturing a printed wiring board according to claim [[3]] 1, wherein each of the waved copper foils has a surface roughness (R_z) of 10 to 20 μm .

5. (Previously presented) A method of Claim 1 wherein said waved external copper foils have the surface roughness of a carrier foil used in pressing said laminate.